16. (amended) A chemical-mechanical polishing process for planarizing one or more films formed on a substrate, wherein said thin films are subjected to chemical-mechanical polishing using an abrasive particles slurry, all of said abrasive particles consisting essentially of boehmite, and the residual slurry and contamination are removed by spin cleaning.

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REMARKS

This is a full and timely response to the final Official Action mailed January 23, 2002. Reexamination and reconsideration in light of the above amendments and the following remarks are courteously requested.

By the foregoing amendment, claims 12 and 16 have been amended. No claims are added or canceled. Thus, claims 12 to 14, 16 to 20, 22, and 24 to 27 are currently pending for the Examiner's consideration.

The current amendment represents discussions between the Examiner and Applicants' representative, and are not believed to present new issues for the Examiner's consideration. More particularly, it was previously attempted to limit the scope of claims 12 and 16 in the manner set forth in the present amendment, by adding the language "consisting of" or "consisting essentially of" to the respective claims. However, the Examiner pointed out in the final Official Action that the prior amendment could be read two different ways, but

considered the claims under both interpretations. Thus, the present amendment is made in order to clarify which of the Examiner's interpretations of the claim is intended, and should not raise new issues for the Examiner's consideration. It is consequently respectfully requested that the present amendment be entered.

Rejections Under 35 U.S.C. § 112, First Paragraph

In the office Action, the Examiner rejected claims 14, 20, 22, and 24 to 27 as containing subject matter which was not described in the specification, and as not enabling a person of ordinary skill in the art to make and/or use the claimed invention. These rejections are respectfully traversed, for the reasons set forth in the accompanying Appeal Brief.

Rejections Under 35 U.S.C. §§ 102(a), (b), or (e)/103(a)

The Examiner rejected claims 12 to 14 as being unpatentable over Cote in view of Wang. Claim 13 is further rejected as being unpatentable over Cote and Wang, further in view of a cited Alcoa Technical Paper (Wefers). Claims 16 to 20 are rejected as being unpatentable over Wang in view of Krussel and Winebarger. Claim 19 is rejected as being unpatentable over the combination of references applied against claims 16 to 20, above, and further in view of Wefers. Claims 12 to 14 are rejected as being anticipated by, or

unpatentable over Yamada. Claim 13 is rejected as being unpatentable over Yamada in view of Wefers. These rejections are respectfully traversed for the reasons set forth in the Appeal Brief accompanying this paper.

For the foregoing reasons and the reasons set forth in the Appeal Brief filed herewith, all the claims now pending in the present application are believed to be clearly patentable over the prior art of record. Accordingly, favorable reconsideration of the claims in light of the above remarks is courteously solicited. If the Examiner has any comments or suggestions that could place this application in even better form, the Examiner is requested to telephone the undersigned attorney at the below-listed number.

Respectfully submitted,

DATE: 23 July 2002

42,314

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Appendix
Amendments to the Claims

12. (amended) A chemical-mechanical polishing process for planarizing one or more thin films formed on a substrate, wherein the chemical-mechanical polishing is performed using an abrasive particles basic slurry [containing], all of said abrasive particles consisting of boehmite.

16. (amended) A chemical-mechanical polishing process for planarizing one or more films formed on a substrate, wherein said thin films are subjected to chemical-mechanical polishing using an abrasive particles slurry [containing], all of said abrasive particles consisting essentially of boehmite, and the residual slurry and contamination are removed by spin cleaning.